

AN1014

Measuring Small Changes in Capacitive Sensors

Author: Kumen Blake and Steven Bible Microchip Technology Inc.

INTRODUCTION

Target Audience

This application note is intended for hardware and firmware design engineers that need to detect small changes in capacitance.

Goals

- Detect small capacitance changes (e.g., 0.001 pF)
- Estimate capacitances (i.e., 10 pF to 1 nF)
- Use minimal number of external components
- · Create simple firmware solution
- Show design trade-offs and alternative circuits

Description

This application note shows a switched capacitor circuit that uses a PICmicro[®] microcontroller, and minimal external passive components, to measure small changes in capacitance. The values are very repeatable under constant environmental conditions.

The design is measured to verify the theory and design choices. Some design alternatives and modifications are explored. Information on the circuit board and firmware used in the measurements is included.

References to documents that treat these subjects in more depth and breadth have been included in the "**References**" section.

SWITCHED CAPACITOR SOLUTION

This section describes a circuit that is appropriate for measuring small changes in capacitance (e.g., 0.001 pF) for relatively small capacitors (i.e., 10 pF to 10 nF).

Switched Capacitor Preliminaries

Figure 1 shows the general situation when a grounded, switched (sensing) capacitor (C_{SEN}) transfers energy from a voltage source (V_S) to an output integrating (storage) capacitor (C_{INT}). Each time one of the switches closes, charge is transferred to, or from, C_{SEN} to equalize the voltages. The period of a complete switching cycle is T_{SW} .



FIGURE 1: Diagram of a Grounded, Switched Capacitor.

 $C_{\rm INT}$ is chosen to be much larger than C_{SEN} , so $V_{\rm INT}$ can be considered to be approximately constant during any one switching cycle. The charges transferred per time $(Q_S/T_{SW}$ and $Q_{\rm INT}/T_{SW})$ can be approximated, on the average, as currents flowing between two voltages (V_S and V_{INT}). Thus, the switches and C_{SEN} can be modeled as a series resistance (R_{SEN} in Equation 1 and Figure 2):

EQUATION 1:



FIGURE 2: Equivalent Model for the Grounded, Switched Capacitor.

Hardware

CIRCUIT

Figure 3 shows the circuit used to measure a capacitive sensor. The PICmicro[®] microcontroller provides the timing, internal voltage reference and comparator to measure R-C step response times.





Capacitor Sensor Circuit.

The voltages in the diagram are related as follows:

EQUATION 2:

$$V_{SEN} = V_{P1} = V_{P2}$$
$$V_{INT} = V_{SEN} - V_{P4}$$

The pin assignments used on the PCB in **Appendix B:** "Circuit Board" are as follows:

- P1 = RC4
- P2 = RC1
- P3 = RC3
- P4 = RC2

The circuit has two measurement steps:

- · First Measurement Step (Switching)
 - C_{SEN} is used as a switched capacitor resistor, which causes the voltage, $V_{INT\!,}$ to exponentially approach V_{DD} (starting at 0V)
- Second Measurement Step (Calibration)
 - R_{CAL} is grounded, causing V_{INT} = V_{SEN} to exponentially approach 0V

FIRST MEASUREMENT STEP (SWITCHING)

The simplified model of the first measurement step is described in Equation 3 and Figure 4. C_{SEN} is used as a switched capacitor resistor, and C_{INT} is the integrating capacitor. Pin P3 is put in a high-impedance state so that R_{CAL} doesn't affect the measurements. The voltage across C_{INT} (V_{INT}) starts at 0V (after a preliminary discharge time) and exponentially approaches V_{DD} . The comparator detects when V_{INT} reaches an upper reference voltage (V_{RH}), and the microcontroller measures the number of switching periods (k_1 periods of length T_{SW}) needed to reach that point.

EQUATION 3:

$$V_{INT} = 0V, \quad t < 0$$

$$\approx V_{DD}(1 - e^{-t/\tau I}), \quad t \ge 0$$

$$k_I \approx \frac{\ln(V_{DD}/(V_{DD} - V_{RH}))}{C_{SEN}/C_{INT}}$$
Where:
$$C_{SEN} \quad << \quad C_{INT}$$

$$R_{SEN} \quad = \quad T_{SW} / C_{SEN}$$

$$\tau_1 = R_{SEN}C_{INT}$$

T_{SW} = Switching Period



FIGURE 4:

Equivalent Model for VINT.

The PICmicro[®] microcontroller produces a switch clock (CKsw) with period T_{SW}. This clock signal alternately selects between two cycles: the charging cycle and the sharing cycle. The resistor, R_{CAL}, is left floating, so it doesn't affect this measurement. Table 1 gives the pin states for the two cycles during a typical switching

period (T_{SW}). Figure 5 shows typical waveforms for the first measurement cycle (see Figure 3 for the voltages shown). V_{P4} shows an R-C step response because R_{CAL} interacts with the I/O port pin capacitance at P4.

TABLE 1: PIN STATES

	Pin States			
Cycles	P1	P2	P3	P4
Charging Cycle	1	input	hi-Z	hi-Z
Sharing Cycle	hi-Z	input	hi-Z	0

Note 1: The Charge Cycle charges $C_{\mbox{\scriptsize SEN}}$ to the voltage $V_{\mbox{\scriptsize DD}}.$

- 2: The Share Cycle shares the charge between C_{SEN} and $C_{INT^{\!\!}}$ which slowly increases $V_{INT^{\!\!}}$
- **3:** P2 is high impedance, and is always connected to the comparator.
- 4: Not shown are transition states between the cycles; see Table 3.



FIGURE 5: Timing.

Many switching periods (T_{SW}) are needed to increase V_{INT} until it reaches the higher reference voltage (V_{RH}). The microcontroller counts the number of switching periods (T_{SW}) needed for V_{INT} to increase from V_{RL} to V_{RH}; the result is placed in the counter k₁ (the

"switching count"). The time needed for V_{INT} to reach V_{RH} is $k_1 T_{SW}$. As will be shown later, k_1 is a measure of the ratio C_{SEN} / C_{INT} .

Figure 6 and Figure 7 illustrate the sequence discussed above. Notice how the integrator voltage (V_{INT}) looks like a series of stair steps due to the digital control provided by the microcontroller. When C_{INT} is very large (compared to C_{SEN}), these steps are very small, and the waveform is well approximated by an R-C step response. $V_{SEN} = V_{DD}$ during the first part of the switching cycle (charging C_{SEN}), and $V_{SEN} = V_{INT}$ during the second part of switching cycle (sharing charge with C_{INT}).

 C_{INT} is set much lower in these figures than it would be for a practical circuit in order to make the switch response easier to see. The parameters used to produce these figures are:

- C_{INT} = 1.0 nF
- C_{SEN} = 100 pF
- T_{SW} = 5.0 μs
- V_{DD} = 5.0V



FIGURE 6: First Measurement Step Example $- V_{INT}$ Voltage.



FIGURE 7: First Measurement Step Example – V_{SEN} Voltage.

The parasitic input capacitances (C_{PAR}) at each of the microcontroller input pins, P1–P3, are in parallel with C_{SEN}. The parasitic capacitance at pin P4 (also C_{PAR}) produces a current in the same direction as C_{SEN}, and sees the same voltage change during switching as the other parasitic capacitances, so it can also be considered to be in parallel with C_{SEN}. Thus, for greater accuracy for small C_{SEN}, it can be replaced by the sum (C_{SEN} + 4C_{PAR}) in all of the equations for the first measurement step. R_{CAL} is chosen so that the time constant, R_{CAL}C_{PAR}, is much shorter than the switching period, T_{SW}. The equation for k₁ becomes:

EQUATION 4:

$$k_1 \approx \frac{ln(V_{DD} / (V_{DD} - V_{RH}))}{(C_{SEN} + 4C_{PAR}) / C_{INT}}$$

SECOND MEASUREMENT STEP (CALIBRATION)

The model of the second measurement step is described in Equation 5 and Figure 8. R_{CAL} , C_{INT} and C_{SEN} are all grounded (connected in parallel), and no energy is transferred to these parts. The voltage, V_{INT} , starts at a high value (V_{RH}) and decays exponentially towards ground. The comparator detects when V_{INT} has reached a low value (V_{RL}). The microcontroller measures the time elapsed (k_2 instruction periods of length, T_{CLK}).

EQUATION 5:

$$V_{INT} = V_{SEN} = V_{RH}, \quad t < 0$$

$$= V_{RH}e^{-t/\tau^2}, \quad t \ge 0$$

$$k_2 \approx \frac{R_{CAL}(C_{INT} + C_{SEN})ln(V_{RH}/V_{RL})}{T_{CLK}}$$

Where:
$$\tau_2 = R_{CAL}(C_{INT} + C_{SEN})$$





Model for VINT.

The PICmicro microcontroller counts the number of its internal instruction cycles (CLK, with period, T_{CLK}) needed for V_{INT} to decrease from V_{RH} to V_{RL} . This result is placed in the counter, k_2 (the "calibration count"). The time needed is k_2T_{CLK} . As will be shown later, k_2 is a measure of the sum $C_{INT} + C_{SEN}$; it is used to correct for errors in C_{INT} (process variation, temperature drift, aging, etc.). Table 2 gives the pin states for this measurement step.

TABLE 2:PIN STATES

	Pin States			
Cycles	P1	P2	P3	P4
Calibration Cycle	hi-Z	input	0	0

Note 1: The Calibration Cycle discharges $C_{\rm INT}$ and $C_{\rm SEN},$ through R_{CAL} to ground, until it reaches the voltage $V_{RL}.$

2: P2 is high impedance, and is always connected to the comparator.

Figure 9 illustrates the measurement step discussed above. $C_{\rm INT}$ is set much lower in this figure than it would be for a practical circuit in order to make the waveform easier to interpret. The parameters used to produce this figure are:

- C_{INT} = 1.0 nF
- C_{SEN} = 100 pF
- T_{CLK} = 0.5 μs
- V_{DD} = 5.0V





The parasitic input capacitances (C_{PAR}) at each of the microcontroller input pins, P1–P3, are in parallel with C_{SEN}. The parasitic capacitance at pin P4 is shorted to ground. Thus, for greater accuracy for small C_{SEN}, it can be replaced in all of the equations for the second measurement step by the sum (C_{SEN} + 3C_{PAR}). The equation for k₂ becomes:

EQUATION 6:

$$k_2 \approx \frac{R_{CAL}(C_{INT} + C_{SEN} + 3C_{PAR})\ln(V_{RH} / V_{RL})}{T_{CLK}}$$

Measurement Resolution

As a general rule, the higher the counts k_1 and k_2 are, the greater the resolution of the measured $C_{\rm INT}$ and $C_{\rm SEN}$. Larger $C_{\rm INT}$ produces larger k_2 counts and better resolution. Smaller $C_{\rm SEN}$ produces larger k_1 counts and greater resolution; this is opposite the behavior of R-C decay timing methods [7], and is a significant advantage for this method. When $C_{\rm SEN}$ becomes smaller than $4C_{\rm PAR}$, however, its resolution becomes worse.

The resolution for C_{SEN} and C_{INT} can be made higher by increasing C_{INT} and R_{CAL} . R_{CAL} needs to be small enough so that the parasitic capacitance at pin P3 of U₁ can settle in time, (i.e., $10R_{CAL}C_{PAR} < T_{SW}/2$).

Equation 7 shows approximations to the normalized resolution for these capacitances $(\Delta C_{INT}/C_{INT}$ and $\Delta C_{SEN}/C_{SEN})$ as a function of a change in the number of counts $(\Delta k_1 \text{ and } \Delta k_2)$. Figure 10 and Figure 11 show the same results in graphic form for a design optimized for C_{SEN} near 180 pF (and $C_{PAR}\approx7.7$ pF). Notice that the Δk_1 increment is -1 in Figure 10; this means C_{SEN} decreases when k_1 increases.

EQUATION 7:

$$\begin{split} \frac{\Delta C_{INT}}{C_{INT}} &\approx \frac{\Delta k_1}{k_1} \bullet \frac{C_{SEN} + 4C_{PAR}}{C_{INT}}, \quad \Delta k_2 = 0 \\ \frac{\Delta C_{INT}}{C_{INT}} &\approx \frac{\Delta k_2}{k_2}, \quad \Delta k_1 = 0 \\ \frac{\Delta C_{SEN}}{C_{SEN}} &\approx \frac{\Delta k_1}{k_1} \bullet \frac{C_{SEN} + 4C_{PAR}}{C_{SEN}}, \quad \Delta k_2 = 0 \\ \frac{\Delta C_{SEN}}{C_{SEN}} &\approx \frac{\Delta k_2}{k_2} \bullet \frac{C_{SEN} + 4C_{PAR}}{C_{SEN}}, \quad \Delta k_1 = 0 \end{split}$$



FIGURE 10: Example – Normalized C_{SEN} Resolution ($\Delta C_{SEN}/C_{SEN}$) vs. Δk_1 and Δk_2 .



FIGURE 11: Example – Normalized C_{INT} Resolution ($\Delta C_{INT}/C_{INT}$) vs. Δk_1 and Δk_2 .

FIRMWARE

The firmware discussed in this section is designed for the circuit in **Appendix B: "Circuit Board**", and is implemented with the code shown in **Appendix C: "Firmware"**.

Detailed Algorithm

Table 3 shows the algorithm in detail, including the microcontroller's pin states. State 3 and State 4 are the first measurement step (the two parts to the switching

cycle), and State 5 is the second measurement step. The initialization, calculation, output and sleep states are needed for complete functionality.

The microcontroller pin assignments in Appendix B: "Circuit Board" are:

- P1 = RC4
- P2 = RC1
- P3 = RC3
- P4 = RC2

Circuit State		Pin States				• "	
		P1	P2	P3	P4	Action	
1. Initialize		_	_	—		Initialize PICmicro [®] microcontroller	
						Configure hardware settings	
						Initialize counts (k ₁ and k ₂) to zero (Note 3), (Note 4)	
2.	Discharge	0	input	0	0	Discharge C _{INT} and C _{SEN} to 0V	
				Allow time for capacitors to discharge to 0		Allow time for capacitors to discharge to 0V	
3.	Charge	hi-Z	input	hi-Z	hi-Z	Quick Transition (avoid crowbar current)	
		1	input	hi-Z	hi-Z	Charge C_{SEN} to V_{DD}	
						Allow time for C _{SEN} to charge	
						Increment k ₁	
4.	Share Charge	hi-Z	input	hi-Z	hi-Z	Quick Transition (avoid crowbar current)	
	hi-Z input hi-Z 0 Share charge between C _{SEN} and C _{INT}		Share charge between C _{SEN} and C _{INT}				
						Allow time for C_{INT} and C_{SEN} to share charges	
						IF (V _{P2} < V _{RH}) THEN (GOTO State 3) (Note 1)	
5.	Calibrate	hi-Z	input	0	0	Calibrate (C _{INT} + C _{SEN}) value using R _{CAL}	
						(increment k_2 at each T_{CLK} period) UNTIL ($V_{P2} < V_{RL}$) (Note 2)	
6.	Calculate	0	input	0	0	Calculate capacitances	
	(Note 5)					(discharge C _{INT} and C _{SEN} to 0V)	
						Calculate $A_R = C_{SEN}/C_{INT}$ from k_1 and circuit values	
						Calculate $A_S = C_{INT} + C_{SEN}$ from k_2 and circuit values	
						Calculate C _{INT} and C _{SEN}	
7.	Output	0	input	0	0	Output results (k ₁ , k ₂ , C _{INT} and C _{SEN})	
						(discharge C _{INT} and C _{SEN} to 0V)	
8. Sleep 0 input 0 0 Put circuit into Sleep mode		Put circuit into Sleep mode					
						(continue to discharge C _{INT} and C _{SEN} to 0V)	
						Power Down	
						Stay in sleep for fixed amount of time (e.g., 1 minute)	
						Power Up	
						GOTO State 1	

Note 1: V_{RH} is the upper V_{REF} value used by the comparator (0.6875 V_{DD} = 3.438V).

2: V_{RL} is the lower V_{REF} value used by the comparator (0.25 V_{DD} = 1.25V).

3: k_1 is the "share charge cycles" counter; it increments once for each time states 3 and 4 are executed ($T_{SW} = 6.5$).

4: k₂ is the "calibrate cycles" counter; it increments once for each PICmicro instruction cycle (T_{CLK} = 0.5 μs).

5: The firmware in **Appendix C: "Firmware**" does not include the calculation of C_{INT} and C_{SEN}. It outputs k₁ and k₂ via the SPI bus, and leaves the conversion to capacitance to another routine written by the user.

TABLE 3: ALGORITHM

Flow Chart

Figure 12 shows the flow chart for the firmware in **Appendix C: "Firmware"**, which is an abbreviated version of the algorithm in Table 3.



Capacitance Extraction Equations

The extraction equations in this section are not implemented in the firmware shown in **Appendix C:** "**Firmware**". It is up to the user to write a routine that accepts k_1 and k_2 , then calculates C_{INT} and C_{SEN} .

The extraction equations for $\mathsf{C}_{\mathsf{INT}}$ and $\mathsf{C}_{\mathsf{SEN}}$ are:

EQUATION 8:

Assumption:

 $C_{INT} >> C_{SEN} + 4C_{PAR}$ Pre-calculated Constants:

$$B_{I} = ln\left(\frac{V_{DD}}{V_{DD} - V_{RH}}\right)$$
$$B_{2} = \frac{T_{CLK}}{R_{CAL} ln(V_{RH}/V_{RL})}$$

Extraction Equations:

$$\begin{aligned} A_R &= B_1 / k_1 \\ A_S &= B_2 k_2 \\ C_{INT} &\approx \frac{A_S + C_{PAR}}{1 + A_R} \\ &\approx A_S, \quad (Simplified formula) \\ C_{SEN} &\approx A_R C_{INT} - 4 C_{PAR} \end{aligned}$$

The accuracy of these extractions depend on:

- The measurement resolution (k₁ and k₂)
- Estimating the correct value for C_{PAR}
- Keeping C_{SEN} in the recommended range of values

The main difficulty in implementing this algorithm is caused by the division needed to calculate A_R . The references [9-12] discuss general division routines. Reference [13] discusses one approach to using piecewise linear approximation tables in microcontrollers.

MEASURED RESULTS

Setup

Measurements were made with the following nominal circuit design parameters:

- C_{INT} = 1.0 µF
- C_{SEN} = 10 pF to 10 nF
- R_{CAL} = 3.01 kΩ
- T_{SW} = 5.0 μs
- T_{CLK} = 0.5 μs
- V_{DD} = 5.0V
- V_{RL} = 1.250V
- V_{RH} = 3.438V

These measurements were made with the board discussed in **Appendix B: "Circuit Board"**.

Measured Circuit Parameters

The measured circuit parameters are:

- C_{INT} = 1.082 μF
- C_{PAR} = 7.7 pF
- R_{CAL} = 3.013 k Ω (by the HP3457A)

Appendix A: "Measured Results" gives a complete list of measured k_1 , k_2 and C_{SEN} values.

Oscilloscope Plots

 V_{SEN} was measured with an oscilloscope; the results are plotted in Figure 13. A closer look at the calibration step (R-C decay) is shown in Figure 14.



FIGURE 13: V_{SEN} Time Response with C_{SEN} = 220 pF.



FIGURE 14: V_{SEN} Time Response Detail with C_{SEN} = 220 pF.

Measurement Resolution

Figure 15 shows how well the extracted values of C_{SEN} (including the correction for C_{PAR}) match the values produced by the HP4285A Precision LCR Meter. C_{PAR} was estimated to be 7.6 pF.



FIGURE 15: Extracted Sensor Capacitances.

Tests on the bench verified the excellent resolution of this method. The results were very consistent over a short period of time.

Comparing measurements over a long period of time gave results that were not as consistent. It appears that drift with temperature and capacitor dielectric absorption may cause the inconsistencies.

Measurement Accuracy

The measurement accuracy is not as good as that produced by other circuits. The errors seen on the bench were on the order of $\pm 10 \text{ pF}$ and $\pm 10\%$.

The parasitic capacitance value (about 7.7 pF) significantly affected extracted C_{SEN} values when the latter was smaller (more than 10% error below 300 pF).

The remaining error, at low $\rm C_{SEN}$ values, that can be seen in Figure 15 are caused by leakage currents at the microcontroller pins. The smaller $\rm C_{SEN}$ is, the greater this effect is.

Because the physical mechanisms that degrade the measurement accuracy vary significantly with process, temperature, time and other environmental variables, it is difficult to correct these errors.

DESIGN ALTERNATIVES

Possible Modifications

A list of modifications to the design follows:

- Increase resolution (increase k₁ and k₂)
 - Decrease T_{CLK}
 - Increase CINT
 - Increase R_{CAL}
- · Simplify the circuit and firmware
 - Use simpler extraction equations (e.g., ignore C_{PAR})
 - Remove R_{CAL} and the second measurement step (use the nominal value of C_{INT} in the extractions)

- Increase accuracy
 - Increase T_{SW} for better settling of V_{SEN} and V_{P3}
 - Improve V_{REF} accuracy by measuring the levels, V_{RL} and $V_{RH,}$ with an ADC internal to the microcontroller

Other Circuits

One common approach using a microcontroller is to measure the R-C step response time [7]. Its resolution is roughly constant, so it works well for larger capacitances. Its resolution for small capacitances is poor.

Another common approach is to use the capacitor to set an oscillator's frequency. 555 timer oscillators are quite common [8]. They suffer from parasitic capacitance to ground, and the fact that 555 timers from different manufacturers can be quite different. State variable oscillators using op amps are also used for applications demanding higher precision [3, 6]. They are more parasitic insensitive, but use many more external components.

The application note, AN990 [4], gives an overview of analog sensor conditioning circuits. It includes additional circuits for capacitive sensors.

SUMMARY

This application note gives hardware and firmware design engineers a circuit that detects small changes in capacitance (small values). This circuit gives consistent results over a short time frame, especially when the environment is not rapidly changing.

The design is simple and low cost; it only needs a PICmicro microcontroller and very few passive components. It uses the microcontroller to implement a switched capacitor circuit that gives more resolution to small capacitances.

Measurements of an actual circuit illustrate the operation of this circuit, and its resolution.

A discussion of alternate circuits help the designer select the best circuit for an application. Suggested design modifications help the designer choose a more appropriate design point.

Information on the circuit board and firmware used in the measurements is included in the appendicies.

REFERENCES

General Sensors

- [1] "The OMEGA[®] Made in the USA Handbook™", Vol. 1, OMEGA Engineering, Inc., 2002.
- [2] "The OMEGA[®] Made in the USA Handbook™", Vol. 2, OMEGA Engineering, Inc., 2002.
- [3] AN866, "Designing Operational Amplifier Oscillator Circuits For Sensor Applications", Jim Lepkowski; Microchip Technology Inc., DS00866, 2003.
- [4] AN990, "Analog Sensor Conditioning Circuits An Overview", Kumen Blake, Microchip Technology Inc., DS00990, 2005.
- [5] AN512, "Implementing Ohmmeter/Temperature Sensor", Doug Cox; Microchip Technology Inc., DS00512, 1997.
- [6] AN895 "Oscillator Circuits For RTD Temperature Sensors", Ezana Haile and Jim Lepkowski; Microchip Technology Inc., DS00895, 2004.

Capacitive Sensors

- [7] AN611, "Resistance and Capacitance Meter Using a PIC16C622", Rodger Richey; Microchip Technology Inc., DS00611, 1997.
- [8] "Measure Relative Humidity With a PIC[®] MCU", Ricardo Jimenez and Claudia Angulo, Design Briefs, Electronic Design, p. 79-80, March 17, 2005.

Math Routines

- [9] AN526, "PIC16C5X / PIC16CXXX Math Utility Routines", Amar Palacherla, Microchip Technology Inc., 1997.
- [10] AN544, "Math Utility Routines", Frank J. Testa, Microchip Technology Inc., 1997.
- [11] AN575, "IEEE 754 Compliant Floating Point Routines", Frank J. Testa, Microchip Technology Inc., 1997.
- [12] AN617, "Fixed Point Routines", Frank J. Testa, Microchip Technology Inc., 1996.
- [13] AN942, "Piecewise Linear Interpolation on PIC12/ 14/16 Series Microcontrollers", John Day and Steven Bible; Microchip Technology Inc., 2004.

Data Sheets

- [14] MCP6001/2/4 Data Sheet, "1 MHz, Low-Power Op Amp", Microchip Technology Inc., DS21733, 2005.
- [15] PIC16F684 Data Sheet, "14-Pin Flash-Based, 8-Bit CMOS Microcontrollers with nanoWatt Technology", Microchip Technology Inc., DS41202, 2004.
- [16] PIC16C745/765 Data Sheet, "8-Bit CMOS Microcontrollers with USB", Microchip Technology Inc., DS41124, 2000.

APPENDIX A: MEASURED RESULTS

Table A-1 shows the results of measuring discrete capacitors with this method. The table shows the nominal values chosen, the capacitance values measured by a HP4285A LCR meter and the resulting counts produced by the circuit described in **Appendix B: "Circuit Board"**. This data is shown in Figure 15.

C.	sen F)	Counts (Note 1)	Extracted C _{SEN} (F) (Note 2)					
Nominal Measured		k ₁	with	without				
0p (open)	—	28,688	47.9p	17.1p				
15p	15.3p	22,880	60.0p	29.3p				
22p	21.4p	21,111	65.0p	34.3p				
27p	28.0p	19,492	70.4p	39.7p				
33p	33.2p	18,425	74.5p	43.8p				
39p	38.5p	17,306	79.3p	48.6p				
47p	48.2p	15,592	88.1p	57.3p				
56p	52.5p	14,944	91.9p	61.2p				
68p	68.2p	13,024	105.4p	74.7p				
100p	97.6p	10,547	130.2p	99.5p				
150p	150.4p	7,644	179.6p	148.9p				
180p	176.6p	6,716	204.4p	173.7p				
220	211.0p	5,792	237.0p	206.3p				
270p	271.6p	4,632	296.4p	265.7p				
330p	318.0p	3,920	350.2p	319.5p				
470p	448.4p	2,863	479.4p	448.7p				
680p	656.0p	1,976	694.5p	663.8p				
1.0n	0.991n	1,351	1.015n	0.985n				
1.5n	1.406n	952	1.441n	1.410n				
2.2n	2.202n	609	2.250n	2.219n				
2.7n	2.550n	488	2.807n	2.776n				
3.3n	3.715n	338	4.048n	4.017n				
3.9n	4.013n	313	4.370n	4.339n				
5.6n	5.874n	215	6.350n	6.319n				
6.8n	6.915n	182	7.493n	7.462n				
10n	9.42n	126	10.79n	10.76n				

TABLE A-1:	LISTING OF MEASURED
	RESULTS

Note 1: For simplicity, the value of k_2 was assumed to be constant and equal to the value measured at 100 pF ($k_2 = 6,890$).

2: The extracted C_{SEN} is shown with (ignoring $4C_{PAR}$) and without (including $4C_{PAR}$) subtracting $4C_{PAR} = 30.7$ pF.

APPENDIX B: CIRCUIT BOARD

The PCB described in this appendix was used for the measurements in "**Measured Results**". PCB design files are available for downloading from Microchip's web site (www.microchip.com):

- AN1014.zip (Contains all of the following files)
 - AN1014_SCH.dxf (schematic)
 - AN1014_PL1.bmp (top silk-screen plot)
 - AN1014_PL2.bmp (top metal plot)
 - AN1014_PL3.bmp (bottom metal plot)
 - AN1014_GER.zip (zipped Gerber files)

B.1 Schematic

The components have reasonable tolerances since this circuit is not accurate. R_CAL is 3.01 k Ω so that the RCALCSEN time constant is about 23 ns, which is much less than T_{CLK} = 500 ns.

The microcontroller pin assignments are:

- P1 = RC4
- P2 = RC1
- P3 = RC3
- P4 = RC2



FIGURE B-1: Schematic.

B.2 Layout Plots



FIGURE B-2:

Top Silk-screen Layer.



FIGURE B-3: Top Metal Layer.



FIGURE B-4:

Bottom Metal Layer.

B.3 Bill of Materials (BOM)

TABLE B-1: BILL OF MATERIALS

Qty	Reference	Description	Manufacturer	Part Number
1	C_SEN	Ceramic Disk or Monolithic Capacitor, Leaded, 0.200" spacing, 10 pF to 1 nF	—	_
1	C1	Ceramic Capacitor, 100 nF, 50V, 10%, X7R, 0805 SMD	Kemet	C0805C104K5RACTU
2	C_INT, C4	Ceramic Capacitor, 1.0 μF, 16V, 10%, X7R, 0805 SMD	Kemet	C0805C105K5RACTU
1	P1	Header, 1 × 14, 0.100" Pitch, Vertical, Gold	Molex/Waldom Electronics	22-28-4143
1	R_CAL	Chip Resistor, 3.01 kΩ, 1/8W, 1%, 0805 SMD	Yageo America	9C08052A3011FKHFT
1	U1	PIC16F684, PICmicro® microcontroller, 14-pin, 20 MHz, PDIP-14	Microchip Technology Inc.	PIC16F684-I/P
2	(for C_SEN)	Pin Receptacle, 0.015" to 0.025" dia., 0.060" Hole dia.	Mill-Max®	0669-0-15-15-30-27-10-0
1	(for U1)	IC Socket, 14-pin DIP, Gold Plated, 0.300", Low Profile	Mill-Max®	115-93-314-41-003000
1	_	Bare Printed Circuit Board	_	—

Note 1: The capacitor, C_SEN, is an arbitrary value inserted into the C_SEN socket pins by the user. The user may try values between 0 pF (open) to 1 μF to observe the circuit's operation, if so desired.

Software License Agreement

The software supplied herewith by Microchip Technology Incorporated (the "Company") is intended and supplied to you, the Company's customer, for use solely and exclusively with products manufactured by the Company.

The software is owned by the Company and/or its supplier, and is protected under applicable copyright laws. All rights are reserved. Any use in violation of the foregoing restrictions may subject the user to criminal sanctions under applicable laws, as well as to civil liability for the breach of the terms and conditions of this license.

THIS SOFTWARE IS PROVIDED IN AN "AS IS" CONDITION. NO WARRANTIES, WHETHER EXPRESS, IMPLIED OR STATU-TORY, INCLUDING, BUT NOT LIMITED TO, IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICU-LAR PURPOSE APPLY TO THIS SOFTWARE. THE COMPANY SHALL NOT, IN ANY CIRCUMSTANCES, BE LIABLE FOR SPECIAL, INCIDENTAL OR CONSEQUENTIAL DAMAGES, FOR ANY REASON WHATSOEVER.

APPENDIX C: FIRMWARE

The firmware file (AN1014.asm) is available for downloading from Microchip's web site at www.microchip.com.

TABLE C-1: MAIN ROUTINE

```
;-----
; Main Program
;-----
MAIN
;-----
; Initialize PICmicro
;-----
    call INITIALIZE
_____
; Initialize Variables
            ------
    bcf FLAG, TRIP
                    ; clear tick counter trip flag.
    bsf INTCON, GIE
                    ; enable global interrupts
MAINLOOP
    ; configure comparator module and voltage reference
    bsf
         STATUS, RPO
                    ; ---- Select Bank 1 -----
         76543210
    ;
    movlw b'10001110'
                    ; configure comparator reference
    movwf VRCON
                    ; CVref Enabled; VRR High Range; VR=0x14
        STATUS, RPO
    bcf
                    ; ---- Select Bank 0 -----
    ;
         76543210
    movlw b'00000010'
                    ; configure comparator module
    movwf CMCON0
    clrf C COUNT L
                    ; clear C_SEN / C_INT ratio count
    clrf C COUNT H
    clrf
         C COUNT U
```

```
TABLE C-1: MAIN ROUTINE (CONTINUED)
```

```
; remove all electrical charges (ground all I/O pins)
       bsf
              STATUS, RPO
                            ; ---- Select Bank 1 -----
                   /----- COM (RC4) digital output
       ;
                   //---- R CAL (RC3) digital output
       ;
                   |//----- C INT (RC2) digital output
       ;
                   xx543210
       ;
       movlw b'00000011'
       movwf
              TRISC
       bcf
              STATUS, RPO
                               ; ---- Select Bank 0 -----
                   /----- COM (RC4) ground
       ;
                   //---- R CAL (RC3) ground
       ;
                   ||/----- C_INT (RC2) ground
       ;
                  xx543210
       ;
              b'00000000'
       movlw
       movwf
             PORTC
       ; long delay to ensure all charges are removed
DELAY LOOP
       btfss FLAG, TRIP
                              ; no, loop
        goto DELAY_LOOP
             FLAG, TRIP
       bcf
                               ; clear tick counter trip flag.
       ; charge C_SEN
CHARGE
       bsf
              STATUS, RPO
                                ; ---- Select Bank 1 -----
                   /----- COM (RC4) digital output
       ;
                   //---- R_CAL (RC3) digital input (high impedance)
       ;
                   ||/----- C_INT (RC2) digital input (high impedance)
       ;
                   ;
                xx543210
       :
       movlw
              b'00001111'
       movwf
              TRISC
                            ; ---- Select Bank 0 -----
             STATUS, RPO
       bcf
                   /----- COM (RC4) Vdd (digital output)
       ;
                   //---- R CAL (RC3) (high impedance)
       ;
                   ||/----- C_INT (RC2) (high impedance)
       ;
                  ;
                xx543210
       ;
       movlw
              b'00010000'
       movwf
              PORTC
       ; share charges between C_SEN and C_INT
       bsf
              STATUS, RPO
                            ; ---- Select Bank 1 -----
                   /----- COM (RC4) digital input (high impedance)
       ;
                   //---- R_CAL (RC3) digital input (high impedance)
       ;
                   |//----- C_INT (RC2) digital output
       ;
                   ;
                xx543210
       ;
             b'00011011'
       movlw
       movwf TRISC
```

```
TABLE C-1: MAIN ROUTINE (CONTINUED)
```

```
; compare voltage across C INT to CVref ( 0.6875 * Vdd )
       bcf
              STATUS, RPO
                                ; ---- Select Bank 0 -----
       btfss
              CMCON0, 7
                                ; is C_SEN > CVref?
        qoto AHEAD
                                 ; yes, we are done, jump ahead
                                 ; no, charge C SEN again and
                                       keep count how many loops
                                 ;
       incf
              C COUNT L, F
                                ; save count
       btfsc
              STATUS, Z
       incf
              C COUNT H, F
              STATUS, Z
       btfsc
       incf C_COUNT_U, F
       goto
              CHARGE
AHEAD
       ; send capacitance count out via SPI
       movfw C COUNT U
              SPI PutByte
       call
       movfw C COUNT H
       call SPI PutByte
       movfw C_COUNT_L
       call SPI_PutByte
       ; discharge ( C_INT + C_SEN ) through R_CAL and time
              TMR1L
       clrf
                                ; clear Timer1
       clrf
              TMR1H
       bsf
              STATUS, RPO
                                ; ---- Select Bank 1 -----
               76543210
       ;
       movlw b'10100110'
                                ; configure comparator reference
       movwf VRCON
                                ; CVref Enabled; VRR Low Range; VR=0x06
                   /----- COM (RC4) digital input (high impedance)
       ;
                   //---- R_CAL (RC3) digital output
       ;
                   ||/----- C_INT (RC2) digital output
       ;
                   ;
               xx543210
       ;
       movlw b'00010011'
       movwf TRISC
       bcf
              STATUS, RPO
                               ; ---- Select Bank 0 -----
                   /----- COM (RC4) (high impedance)
       ;
                   //---- R CAL (RC3) ground
       ;
                   ||/----- C_INT (RC2) ground
       ;
                   ;
                xx543210
       ;
       movlw b'00010000'
       movwf PORTC
       bsf
              T1CON, TMR1ON ; turn on Timer1, begin counting
```

AN1014

```
TABLE C-1: MAIN ROUTINE (CONTINUED)
```

```
; compare voltage across C_INT to CVref ( 0.25 * Vdd )
btfss CMCON0, 7 ; is C_INT > CVref?
goto $ - 1 ; yes, loop
bcf T1CON, TMRION ; no, turn off (stop) Timer1
; send R_CAL discharge counts (time) out via SPI
movfw TMR1H ; report Timer1 contents
call SPI_PutByte
movfw TMR1L
call SPI_PutByte
goto MAINLOOP
```

Note the following details of the code protection feature on Microchip devices:

- · Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WAR-RANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION. QUALITY. PERFORMANCE. MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip's products as critical components in life support systems is not authorized except with express written approval by Microchip. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

Trademarks

The Microchip name and logo, the Microchip logo, Accuron, dsPIC, KEELOQ, microID, MPLAB, PIC, PICmicro, PICSTART, PRO MATE, PowerSmart, rfPIC, and SmartShunt are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

AmpLab, FilterLab, Migratable Memory, MXDEV, MXLAB, PICMASTER, SEEVAL, SmartSensor and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Analog-for-the-Digital Age, Application Maestro, dsPICDEM, dsPICDEM.net, dsPICworks, ECAN, ECONOMONITOR, FanSense, FlexROM, fuzzyLAB, In-Circuit Serial Programming, ICSP, ICEPIC, Linear Active Thermistor, MPASM, MPLIB, MPLINK, MPSIM, PICkit, PICDEM, PICDEM.net, PICLAB, PICtail, PowerCal, PowerInfo, PowerMate, PowerTool, Real ICE, rfLAB, rfPICDEM, Select Mode, Smart Serial, SmartTel, Total Endurance, UNI/O, WiperLock and Zena are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2005, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.



QUALITY MANAGEMENT SYSTEM CERTIFIED BY DNV ISO/TS 16949:2002

Microchip received ISO/TS-16949:2002 quality system certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona and Mountain View, California in October 2003. The Company's quality system processes and procedures are for its PICmicro® 8-bit MCUs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.



WORLDWIDE SALES AND SERVICE

AMERICAS

Corporate Office 2355 West Chandler Blvd. Chandler, AZ 85224-6199 Tel: 480-792-7200 Fax: 480-792-7277 Technical Support: http://support.microchip.com Web Address: www.microchip.com

Atlanta Alpharetta, GA Tel: 770-640-0034 Fax: 770-640-0307

Boston Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

Chicago Itasca, IL Tel: 630-285-0071 Fax: 630-285-0075

Dallas Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

Detroit Farmington Hills, MI Tel: 248-538-2250 Fax: 248-538-2260

Kokomo Kokomo, IN Tel: 765-864-8360 Fax: 765-864-8387

Los Angeles Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608

San Jose Mountain View, CA Tel: 650-215-1444 Fax: 650-961-0286

Toronto Mississauga, Ontario, Canada Tel: 905-673-0699 Fax: 905-673-6509

ASIA/PACIFIC

Australia - Sydney Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

China - Beijing Tel: 86-10-8528-2100 Fax: 86-10-8528-2104

China - Chengdu Tel: 86-28-8676-6200 Fax: 86-28-8676-6599

China - Fuzhou Tel: 86-591-8750-3506 Fax: 86-591-8750-3521

China - Hong Kong SAR Tel: 852-2401-1200 Fax: 852-2401-3431

China - Qingdao Tel: 86-532-8502-7355 Fax: 86-532-8502-7205

China - Shanghai Tel: 86-21-5407-5533 Fax: 86-21-5407-5066

China - Shenyang Tel: 86-24-2334-2829 Fax: 86-24-2334-2393

China - Shenzhen Tel: 86-755-8203-2660 Fax: 86-755-8203-1760

China - Shunde Tel: 86-757-2839-5507 Fax: 86-757-2839-5571

China - Wuhan Tel: 86-27-5980-5300 Fax: 86-27-5980-5118

China - Xian Tel: 86-29-8833-7250 Fax: 86-29-8833-7256

ASIA/PACIFIC

India - Bangalore Tel: 91-80-2229-0061 Fax: 91-80-2229-0062

India - New Delhi Tel: 91-11-5160-8631 Fax: 91-11-5160-8632

India - Pune Tel: 91-20-2566-1512 Fax: 91-20-2566-1513

Japan - Yokohama Tel: 81-45-471- 6166 Fax: 81-45-471-6122

Korea - Gumi Tel: 82-54-473-4301 Fax: 82-54-473-4302

Korea - Seoul Tel: 82-2-554-7200 Fax: 82-2-558-5932 or 82-2-558-5934

Malaysia - Penang Tel: 60-4-646-8870 Fax: 60-4-646-5086

Philippines - Manila Tel: 63-2-634-9065

Fax: 63-2-634-9069 Singapore Tel: 65-6334-8870 Fax: 65-6334-8850

Taiwan - Hsin Chu Tel: 886-3-572-9526 Fax: 886-3-572-6459

Taiwan - Kaohsiung Tel: 886-7-536-4818 Fax: 886-7-536-4803

Taiwan - Taipei Tel: 886-2-2500-6610 Fax: 886-2-2508-0102

Thailand - Bangkok Tel: 66-2-694-1351 Fax: 66-2-694-1350

EUROPE

Austria - Wels Tel: 43-7242-2244-399 Fax: 43-7242-2244-393 Denmark - Copenhagen Tel: 45-4450-2828 Fax: 45-4485-2829

France - Paris Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

Germany - Munich Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

Italy - Milan Tel: 39-0331-742611 Fax: 39-0331-466781

Netherlands - Drunen Tel: 31-416-690399 Fax: 31-416-690340

Spain - Madrid Tel: 34-91-708-08-90 Fax: 34-91-708-08-91

UK - Wokingham Tel: 44-118-921-5869 Fax: 44-118-921-5820

10/31/05